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## Product Change Notification - JAON-14ZGDV728

**Date:** 09 Oct 2016  
**Product Category:** Memory; Analog (Linear & Mixed Signal) AND Interface  
**Notification subject:** CCB 2701 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 160K wafer technology available in 8L PDIP package at MMT assembly site.  
**Notification text:** **PCN Status:** Final notification

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 160K wafer technology available in 8L PDIP package at MMT assembly site.

**Pre Change:**

Using gold (Au) bond wire

**Post Change:**

Using palladium coated copper with gold flash (CuPdAu) bond wire

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	MMT assembly site	MMT assembly site
<b>Wire material</b>	Au wire	CuPdAu wire
<b>Die attach material</b>	CRM-1064L	CRM-1064L
<b>Molding compound material</b>	GE800	GE800
<b>Lead frame material</b>	CDA194	CDA194

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve manufacturability and qualify Palladium coated copper with gold flash (CuPdAu) bond wire

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**  
November 25, 2016 (date code: 1647)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	July 2016				->	October 2016				November 2016			
	27	28	29	30		40	41	42	43	44	45	46	47
Initial PCN Issue Date			X										
Qual Report Availability						X							
Final PCN Issue Date						X							
Estimated Implementation Date													X

**Method to Identify Change:**  
Traceability code

**Qualification Report:**  
Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

**Revision History:**  
**July 19, 2016:** Issued initial notification.  
**October 9, 2016:** Issued final notification. Attached the qualification report. Provided estimated first ship date on November 25, 2016.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):** [PCN\\_JAON-14ZGDV728\\_Qual Report.pdf](#)  
[PCN\\_JAON-14ZGDV728\\_Affected\\_CPN.pdf](#)  
[PCN\\_JAON-14ZGDV728\\_Affected\\_CPN.xls](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_JAON-14ZGDV728
CATALOG_PART_NBR
11AA010-I/P
11AA020-I/P
11AA040-I/P
11AA080-I/P
11AA160-I/P
11AA161-I/P
11LC010-E/P
11LC010-I/P
11LC020-E/P
11LC020-I/P
11LC040-E/P
11LC040-I/P
11LC080-E/P
11LC080-I/P
11LC160-E/P
11LC160-I/P
11LC161-E/P
11LC161-I/P
24AA014H-I/P
24AA014-I/P
24AA01H-I/P
24AA01-I/P
24AA02/P
24AA024H-I/P
24AA024-I/P
24AA025-I/P
24AA025UID-I/P
24AA02H-I/P
24AA02-I/P
24AA02UID-I/P
24AA52-I/P
24C01C/P
24C01C-E/P
24C01C-I/P
24C02C/P
24C02C-E/P
24C02C-I/P
24LC014-E/P
24LC014H-E/P
24LC014H-I/P
24LC014-I/P
24LC01B/P
24LC01B-E/P

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Affected Catalog Part Numbers (CPN)

PCN_JAON-14ZGDV728
CATALOG_PART_NBR
24LC01BH-E/P
24LC01BH-I/P
24LC01B-I/P
24LC024/P
24LC024-E/P
24LC024H-E/P
24LC024H-I/P
24LC024-I/P
24LC025/P
24LC025-E/P
24LC025-I/P
24LC02B/P
24LC02B-E/P
24LC02BH-E/P
24LC02BH-I/P
24LC02B-I/P
24LCS52-I/P
24VL014/P
24VL014H/P
24VL024/P
24VL024H/P
24VL025/P
34AA02-E/P
34AA02-I/P
34LC02-E/P
34LC02-I/P
34VL02/P
MCP4726-E/P
MCP7940M-I/P
MCP7940N-I/P